



(0.80 mm) .0315"

QSE SERIES

HIGH SPEED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/QSE

Insulator Material:

Liquid Crystal Polymer

Terminal Material:

Phosphor Bronze

Plating:

Au or Sn over

50µ" (1.27 µm) Ni

Current Rating:

Contacts:

2 A per pin

(1 pin powered per row)

Ground Plane:

23 A per ground plane

(1 ground plane powered)

Operating Temp Range:

-55°C to +125°C

Voltage Rating:

225 VAC (5 mm Stack Height)

Max Cycles:

100

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (020-060)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

Board Mates:

QTE

Cable Mates:

EQCD, EQDP, EQRF

(See Also Available note)



QTE/QSE 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	9 GHz / 18 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	14 GHz / 28 Gbps
Differential Pair Signaling	-DP	8.5 GHz / 17 Gbps	13.5 GHz / 27 Gbps

*Performance data includes effects of a non-optimized PCB.

**Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com/QSE or contact sig@samtec.com

Blade &
Beam
Design

Integral metal plane
for power or ground

Protocols
Supported

100 GbE

XAUI

PCI Express®

SATA

MGT (Rocket I/O)

InfiniBand™

Download app notes at:

www.samtec.com/appnote

Contact SIG @ samtec.com

for questions on protocols

Final **inch**
CERTIFIED

28+
Gbps

QSE

PINS PER ROW
NO. OF PAIRS

01

PLATING
OPTION

TYPE

A

OTHER
OPTION

-020, -040, -060
(40 total pins per bank = -D)

-014, -028, -042
(14 pairs per bank = -D-DP)

-F

= Gold Flash on
Signal Pins and
Ground Plane, Matte
Tin on tails

-L

= 10µ" (0.25 µm) Gold
on Signal Pins
and Ground Plane,
Matte Tin on tails

-C*

= Electro-Polished
Selective
50µ" (1.27 µm) min
Au over 150µ"
(3.81 µm) Ni on Signal
Pins in contact area,
10µ" (0.25 µm) min
Au over 50µ" (1.27 µm)
Ni on Ground Plane
in contact area,
Matte Tin over 50µ"
(1.27 µm) min Ni on
all solder tails

-D

= Single-
Ended

-D-DP

= Differential
Pair
(-01 only)

-GP

= Guide Post
(-020 only)

-K

= (8.25 mm) .325"
DIA Polyimide
Film Pick &
Place Pad

-TR

= Tape & Reel
Packaging

-L

= Latching Option
(N/A on -042
& -060 positions)

QTE LEAD STYLE	MATED HEIGHT WITH QSE*
-01	(5.00) .197
-02	(8.00) .315
-03	(11.00) .433
-04	(16.00) .630
-05	(19.00) .748
-07	(25.00) .984
-09	(14.00) .551

*Processing conditions
will affect mated
height.

OTHER SOLUTIONS

- Board Spacing Standoffs.
See SO Series

RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality

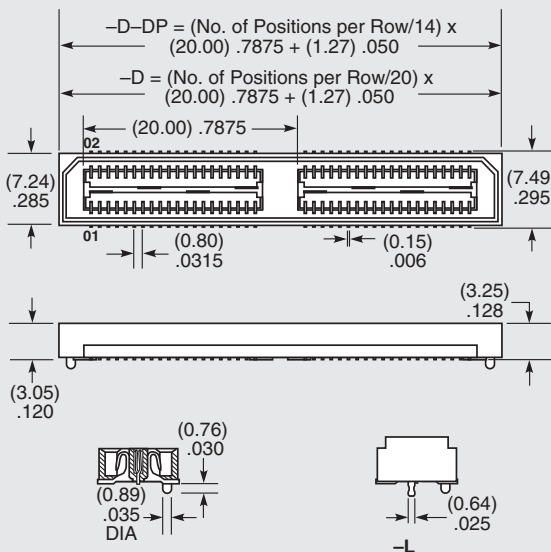


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FILE NO. 090871_0_000

ALSO AVAILABLE (MOQ Required)

- 15 mm, 22 mm and 30 mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
 - 30µ" (0.76 µm) Gold (Specify -H plating for Data Rate cable mating applications.)
 - Edge Mount
 - 56 (-DP), 80, 100 positions per row
 - Guide Posts and Friction Lock options.
 - Retention Option
- Contact Samtec.



*Note: -C Plating passes
10 year MFG testing

Note: Some lengths, styles
and options are non-standard,
non-returnable.